



# 2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- · Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

Δ	D	DI		C	Δ	TI	n	NS	•
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- Freewheeling
- Snubber
- DC/DC converters
- Automotive application

#### **MECHANICAL DATA**

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.027g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	2	Α		
$V_{RRM}$	200 - 1000	V		
I <sub>FSM</sub>	50	Α		
T <sub>J MAX</sub>	150	°C		
Package	SOD-12	.8		
Configuration	Single d	ie		





**SOD-128** 



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2D FSH	RS2G FSH	RS2J FSH	RS2K FSH	RS2M FSH	UNIT
Marking code on the device			RS2DFH	RS2GFH	RS2JFH	RS2KFH	RS2MFH	
Repetitive peak reverse voltage		$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	140	280	420	560	700	V
Forward current		I <sub>F</sub>	2				Α	
Surge peak forward current, single half sine-wave superimposed on rated load $t = 1.0 \text{ms}$			50					А
		I <sub>FSM</sub>	140					Α
Junction temperature		T <sub>J</sub>	-55 to +150			°C		
Storage temperature		T <sub>STG</sub>	-55 to +150				°C	

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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W			
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	73	°C/W			
Junction-to-case thermal resistance	$R_{\Theta JC}$	14	°C/W			

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETI	ER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C		0.93	-	V
	RS2DFSH RS2GFSH RS2JFSH	I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C		1.01	1.30	V
		I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		0.78	-	V
<b>F</b> (1)		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		0.88	1.02	V
Forward voltage <sup>(1)</sup>		I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.98	-	V
	RS2KFSH RS2MFSH	I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C		1.06	1.30	V
		I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		0.83	-	V
		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		0.93	1.05	V
D	(2)	T <sub>J</sub> = 25°C	- I <sub>R</sub>	-	1	μA
Reverse current @ rated V <sub>R</sub> <sup>(</sup>	,	T <sub>J</sub> = 125°C		-	40	μΑ
	RS2DFSH RS2GFSH		t <sub>rr</sub>	-	150	ns
Reverse recovery time	RS2JFSH	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$		-	250	ns
	RS2KFSH RS2MFSH	- III - 0.20/ (		-	500	ns
Junction capacitance	RS2DFSH RS2GFSH RS2JFSH	1MHz, V <sub>R</sub> = 4.0V	CJ	11	-	pF
	RS2KFSH RS2MFSH	, , ,		10	-	pF

#### Notes:

- (1) Pulse test with PW = 0.3ms
- (2) Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING			
RS2xFSH	SOD-128	14,000 / Tape & Reel			

#### Notes:

(1) "x" defines voltage from 200V(RS2DFSH) to 1000V(RS2MFSH)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

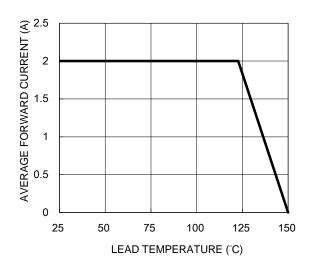


Fig.3 Typical Reverse Characteristics

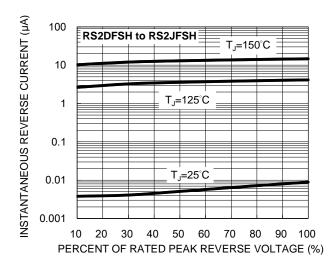


Fig.5 Typical Reverse Characteristics

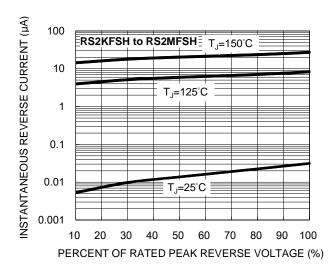


Fig.2 Typical Junction Capacitance

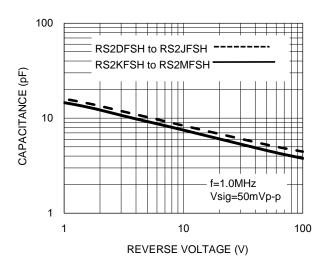


Fig.4 Typical Forward Characteristics

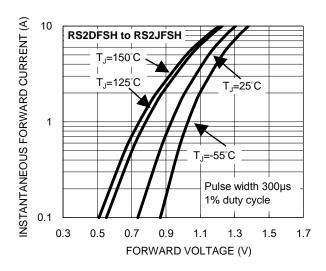
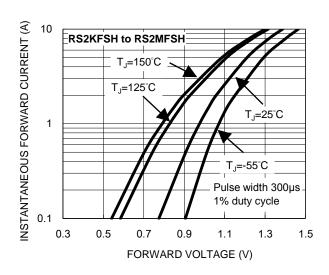


Fig.6 Typical Forward Characteristics

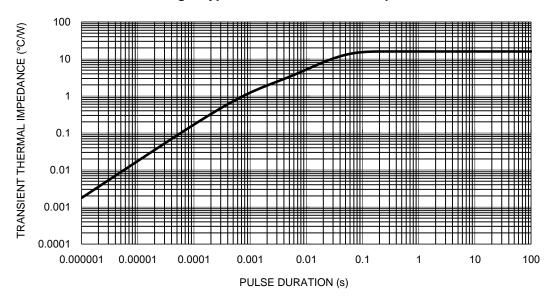




#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

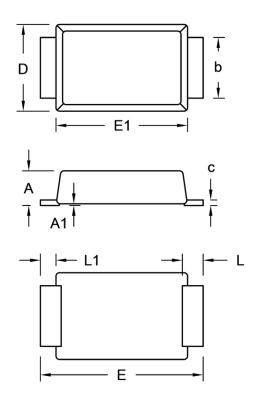
Fig.7 Typical Transient Thermal Impedance



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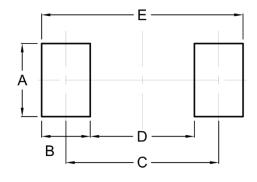
## **PACKAGE OUTLINE DIMENSIONS**

**SOD-128** 



DIM.	Unit	(mm)	Unit (inch)		
DIN.	Min.	Max.	Min.	Max.	
Α	0.90	1.10	0.035	0.043	
A1	0.00	0.10	0.000	0.004	
b	1.60	1.90	0.063	0.075	
С	0.10	0.22	0.004	0.009	
D	2.30	2.70	0.091	0.106	
E	4.40	5.00	0.173	0.197	
E1	3.60	4.00	0.142	0.157	
L	0.40	0.80	0.016	0.031	
L1	0.30	0.60	0.012	0.024	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

## **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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